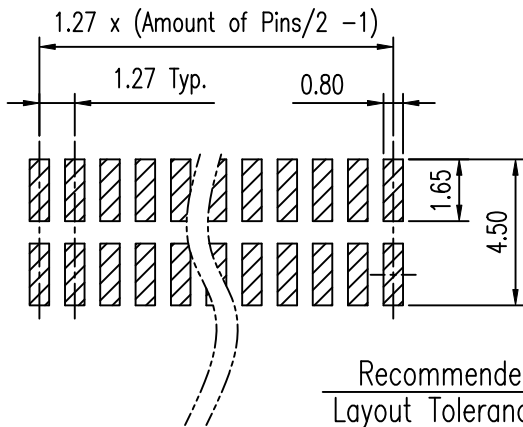
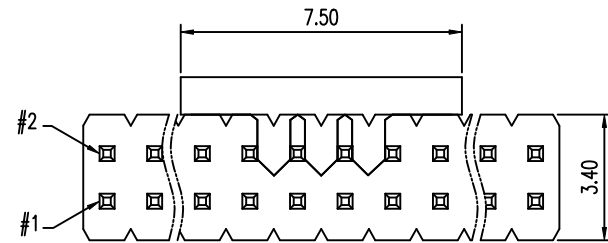
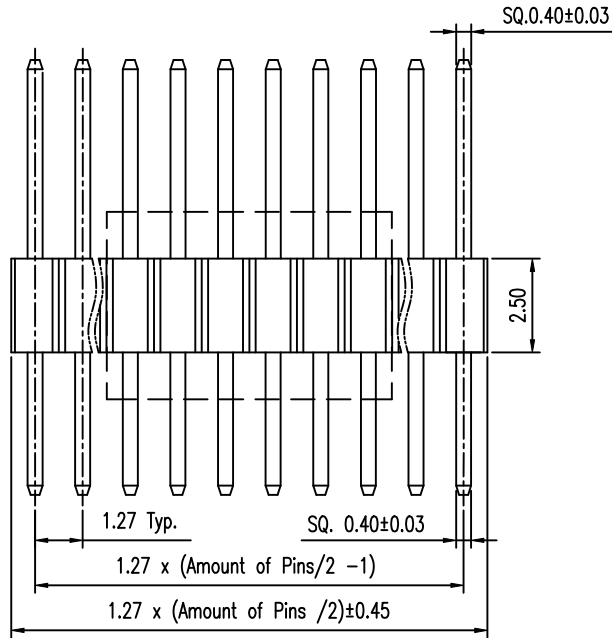
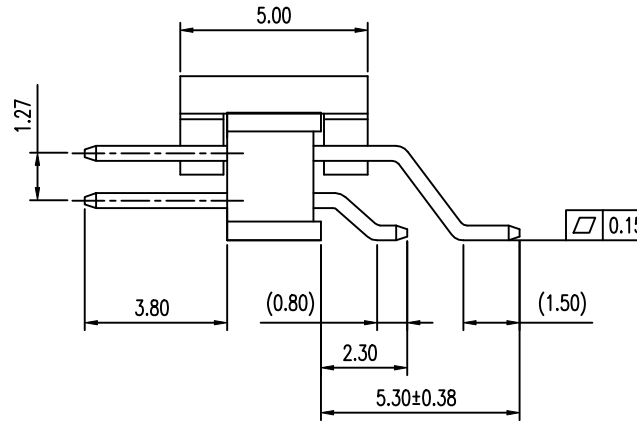




Recommended P.C.B. Layout
Layout Tolerance = ± 0.05 mm



NOTE:

- MATERIAL,
HOUSING: HIGH TEMP PLASTIC, UL94-V0, BLACK
TERMINAL: COPPER ALLOY , SQ=0.40±0.03MM
- FINISH:
TERMINAL: GOLD AT CONTACT,
G/F OVER 1um(40u")MIN Ni OVER ALL
- SPEC.:
PRODUCT SPEC: GS-12-629
PACKING SPEC: GS-14-1420
- THE HSG. WILL WITHSTAND EXPOSURE TO 260C
PEAK TEMP. FOR 10 SEC. IN A CONVECTION, INFRA-RED
OR VAPOR PHASE REFLOW OVEN.
- THE 0.15MM MIN. SOLDER PASTE IS RECOMMENDED
FOR REFLOW SOLDERING.

6. PRODUCT NUMBERING:

20021122 - 0 0 0 XX X X LF

LEAD FREE

PLATING:

1: GOLD FLASH ALL OVER
4: 0.25um(10u")GOLD AT CONTACT
8: 0.76um(30u")GOLD AT CONTACT

PACKING

D: TUBE+ CAP
T: TUBE

PIN COUNT

10, 12, 14,..., 98
(10 - 98 EVERY EVEN PIN)

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		FCI 		www.fciconnect.com					
ltr	ecn no	dr	date	linear	.X ± 0.38			projection 	title 1.27X1.27MM BTB,HEADER UNSTRODED, SMT							
A	T09-1117	S.LIN	09/15/09		.XX ± 0.25											
B	T09-1155	S.LIN	12/03/09		.XXX ± 0.10											
C	T10-0014	S.LIN	01/28/10	angles	0° ±2°											
				dr	STERLING LIN	09/15/09	MM ←→	product family 585			code					
				engr	STERLING LIN	09/15/09		size dwg no			TWN					
				chr	GARY HSIEH	09/15/09		scale			sheet					
				appd	JOSEPH HSIA	09/15/09	NA	A4			20021122			1 of 1		
sheet index	revision sheet		C 1													